

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (π -MOS^{III.5})

2SK2230

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS

CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE APPLICATIONS

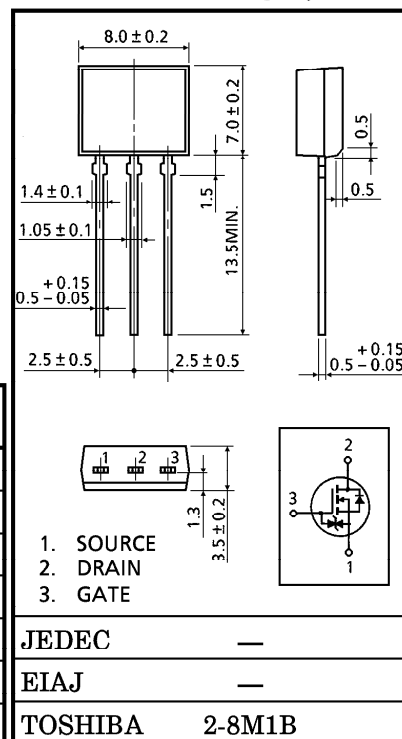
INDUSTRIAL APPLICATIONS

Unit in mm

- Low Drain-Source ON Resistance : $R_{DS(ON)}=1.2\Omega$ (Typ.)
- High Forward Transfer Admittance : $|Y_{fs}|=1.4S$ (Typ.)
- Low Leakage Current : $I_{DSS}=300\mu A$ (Max.) ($V_{DS}=250V$)
- Enhancement-Mode : $V_{th}=2.0\sim 4.0V$ ($V_{DS}=10V$, $I_D=1mA$)

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT
Drain-Source Voltage		V_{DSS}	250	V
Drain-Gate Voltage ($R_{GS}=20k\Omega$)		V_{DGR}	250	V
Gate-Source Voltage		V_{GSS}	± 30	V
Drain Current	DC	I_D	2	A
	Pulse (t=1ms)	I_{DP}	5	A
	Pulse (t=100 μ s)	I_{DP}	12	A
Drain Power Dissipation ($T_a=25^{\circ}C$)		P_D	1.3	W
Channel Temperature		T_{ch}	150	$^{\circ}C$
Storage Temperature Range		T_{stg}	-55~150	$^{\circ}C$



Weight : 0.55g

THERMAL CHARACTERISTICS

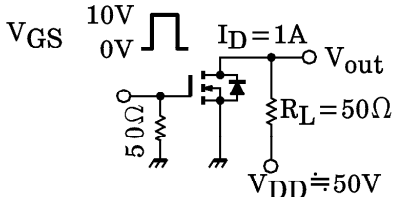
CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel To Ambient	$R_{th(ch-a)}$	96.1	°C / W

THIS TRANSISTOR IS AN ELECTROSTATIC SENSITIVE DEVICE.
PLEASE HANDLE WITH CAUTION.

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● TOSHIBA is continually working to improve the quality and the reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to observe standards of safety, and to avoid situations in which a malfunction or failure of a TOSHIBA product could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent products specifications. Also, please keep in mind the precautions and conditions set forth in the TOSHIBA Semiconductor Reliability Handbook.

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$	—	—	± 100	nA
Drain Cut-off Current		I_{DSS}	$V_{DS} = 250V, V_{GS} = 0V$	—	—	300	μA
Drain-Source Breakdown Voltage		$V_{(BR) DSS}$	$I_D = 10mA, V_{GS} = 0V$	250	—	—	V
Gate Threshold Voltage		V_{th}	$V_{DS} = 10V, I_D = 1mA$	2.0	—	4.0	V
Drain-Source ON Resistance		$R_{DS(ON)}$	$V_{GS} = 10A, I_D = 1A$	—	1.2	2.0	Ω
Forward Transfer Admittance		$ Y_{fs} $	$V_{DS} = 10V, I_D = 1A$	0.5	1.1	—	S
Input Capacitance		C_{iss}	$V_{DS} = 10V, V_{GS} = 0V$ $f = 1MHz$	—	220	—	pF
Reverse Transfer Capacitance		C_{rss}		—	35	—	
Output Capacitance		C_{oss}		—	80	—	
Switching Time	Rise Time	t_r		—	25	—	ns
	Turn-on Time	t_{on}		—	30	—	
	Fall Time	t_f		—	30	—	
	Turn-off Time	t_{off}		—	85	—	
Total Gate Charge (Gate-Source Plus Gate-Drain)		Q_g	$V_{DD} \doteq 200V, V_{GS} = 10V$ $I_D = 2A$	—	7.5	—	nC
Gate-Source Charge		Q_{gs}		—	4.0	—	
Gate-Drain ("Miller") Charge		Q_{gd}		—	3.5	—	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	I_{DR}	—	—	—	2	A
Pulse Drain Reverse Current	I_{DRP}	$t = 1ms$	—	—	5	A
		$t = 100\mu s$	—	—	12	A
Diode Forward Voltage	V_{DSF}	$I_{DR} = 2A, V_{GS} = 0V$	—	—	-1.5	V
Reverse Recovery Time	t_{rr}	$I_{DR} = 2A, V_{GS} = 0V$	—	180	—	ns
Reverse Recovery Charge	Q_{rr}	$dI_{DR} / dt = 100A / \mu s$	—	0.61	—	μC

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